

FG256 Fine-Pitch BGA Package (1.00 mm Pitch)

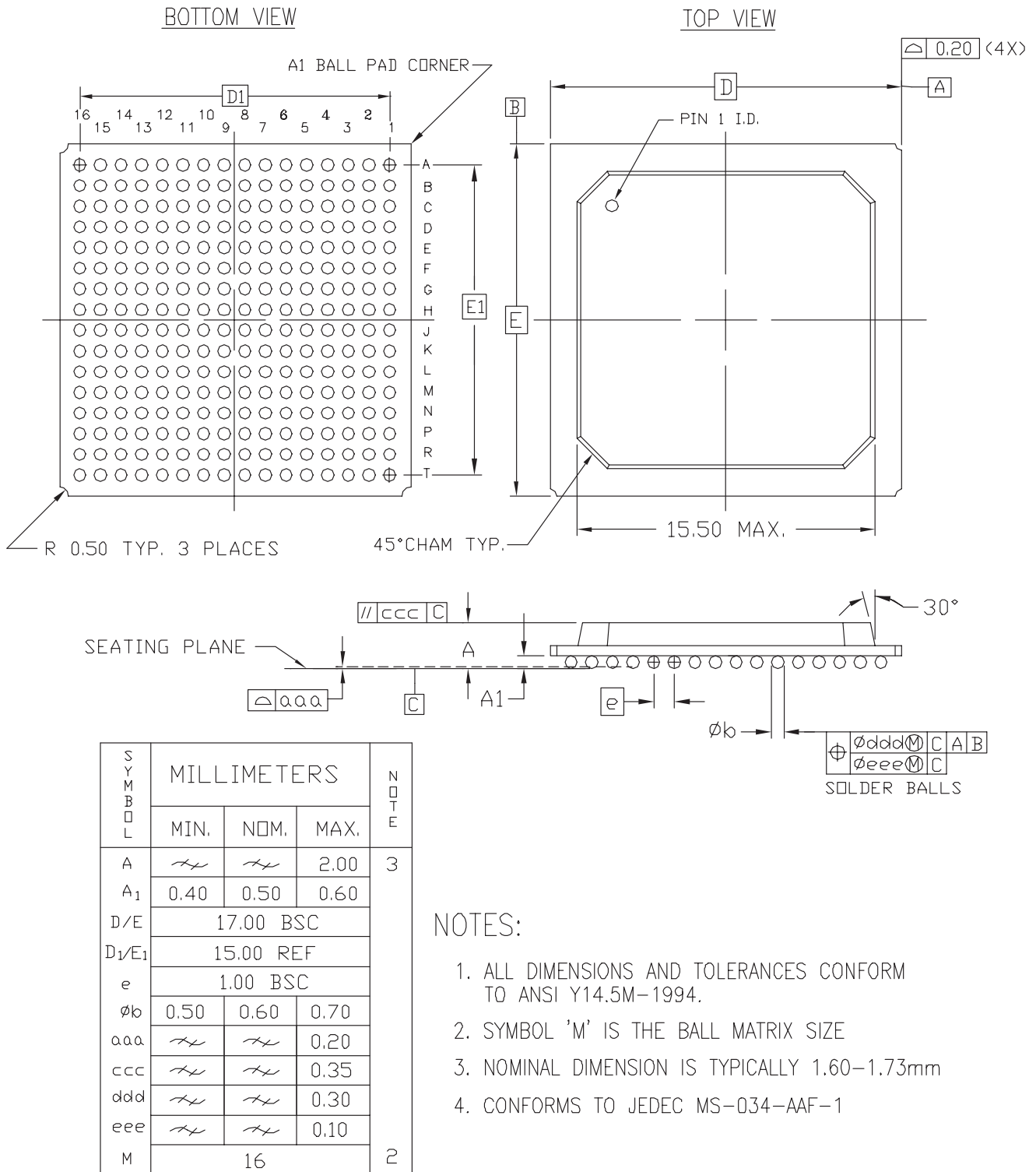


Figure 4-22: FG256 Fine-Pitch BGA Package

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994.
2. SYMBOL 'M' IS THE BALL MATRIX SIZE
3. NOMINAL DIMENSION IS TYPICALLY 1.60-1.73mm
4. CONFORMS TO JEDEC MS-034-AAF-1

FG456 Fine-Pitch BGA Package (1.00 mm Pitch)

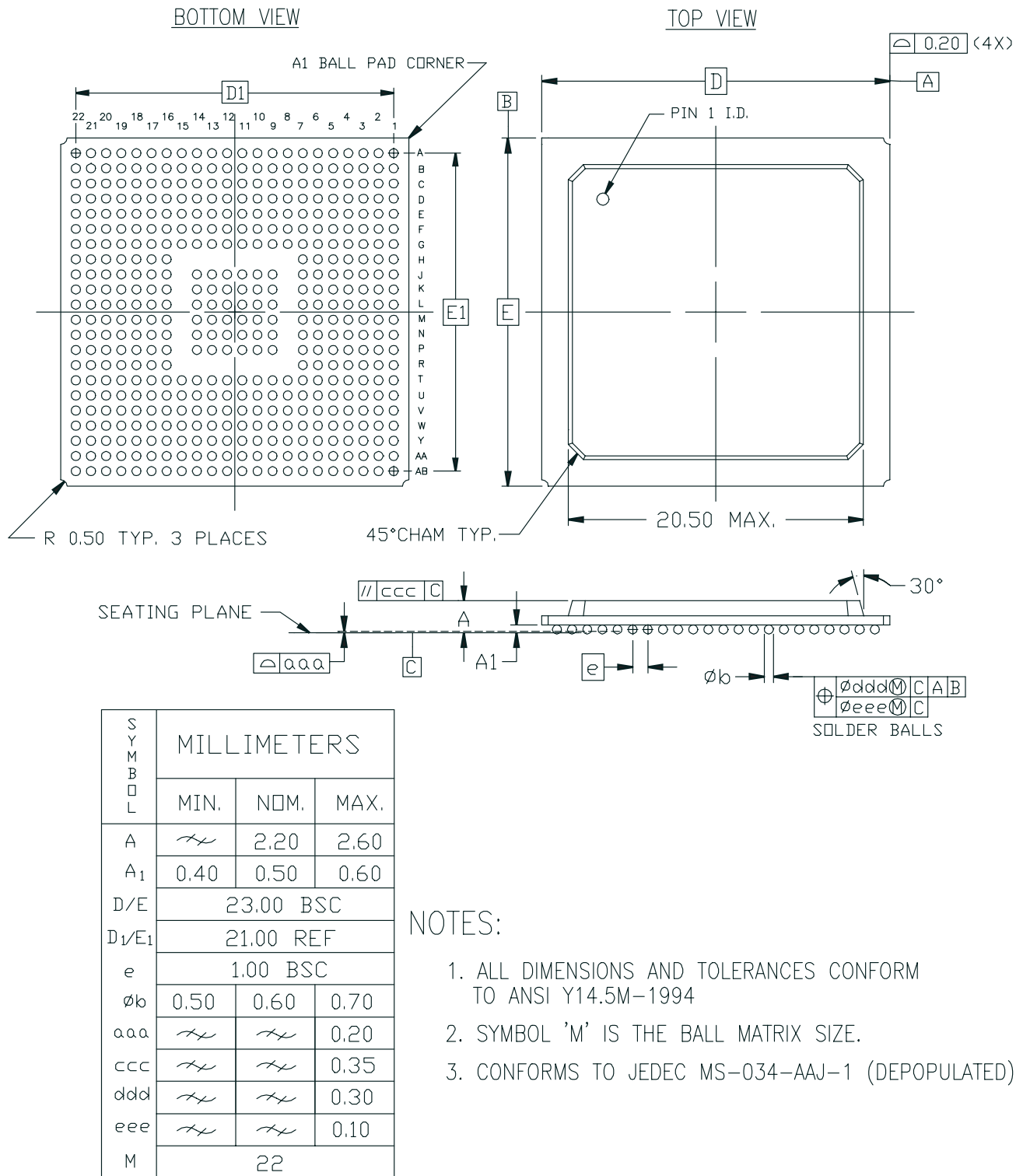


Figure 4-23: FG456 Fine-Pitch BGA Package

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. CONFORMS TO JEDEC MS-034-AAJ-1 (DEPOPULATED)

FF672 Flip-Chip Fine-Pitch BGA Package (1.00 mm Pitch)

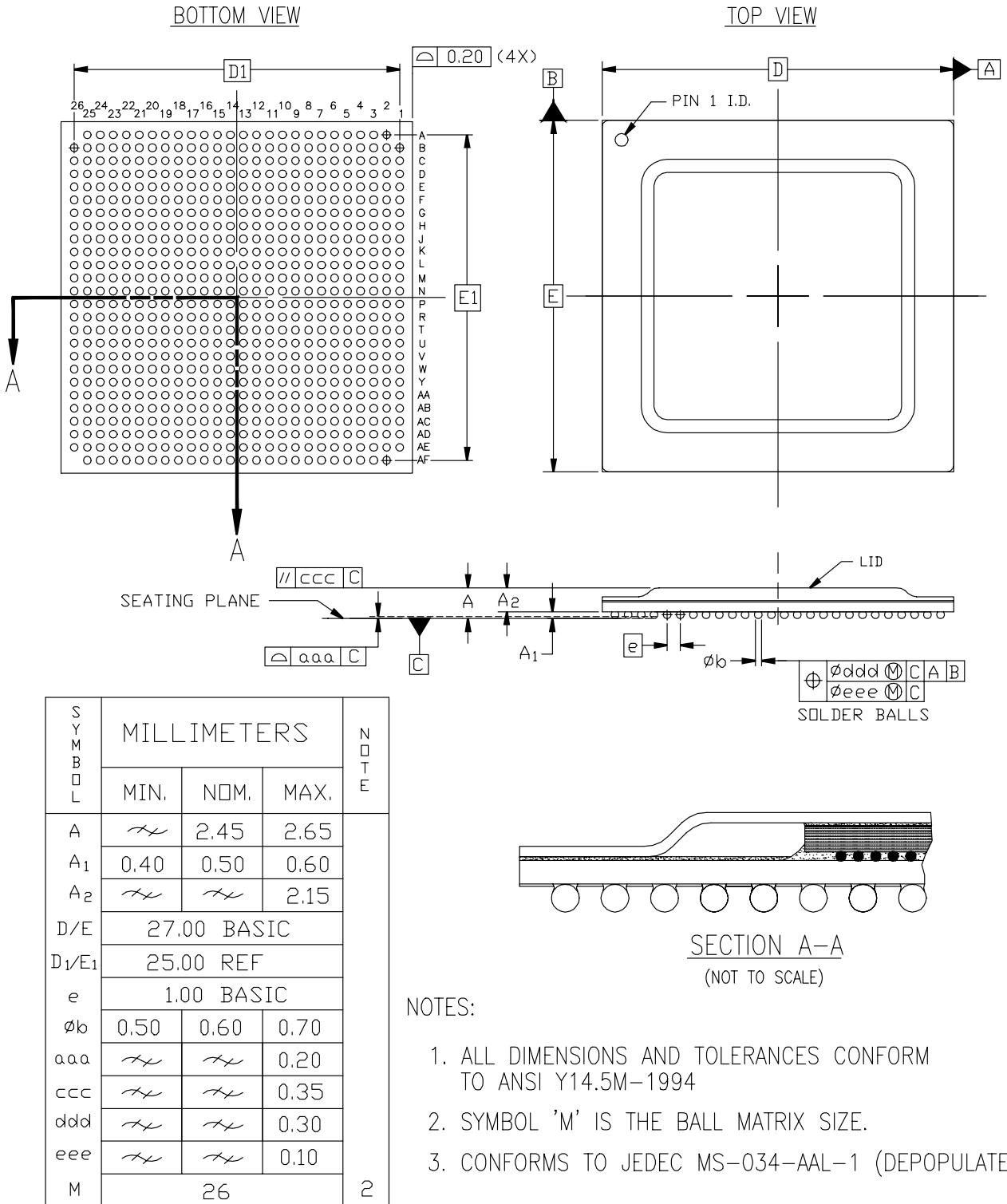


Figure 4-24: FF672 Flip-Chip Fine-Pitch BGA Package

FF896 Flip-Chip Fine-Pitch BGA Package (1.00 mm Pitch)

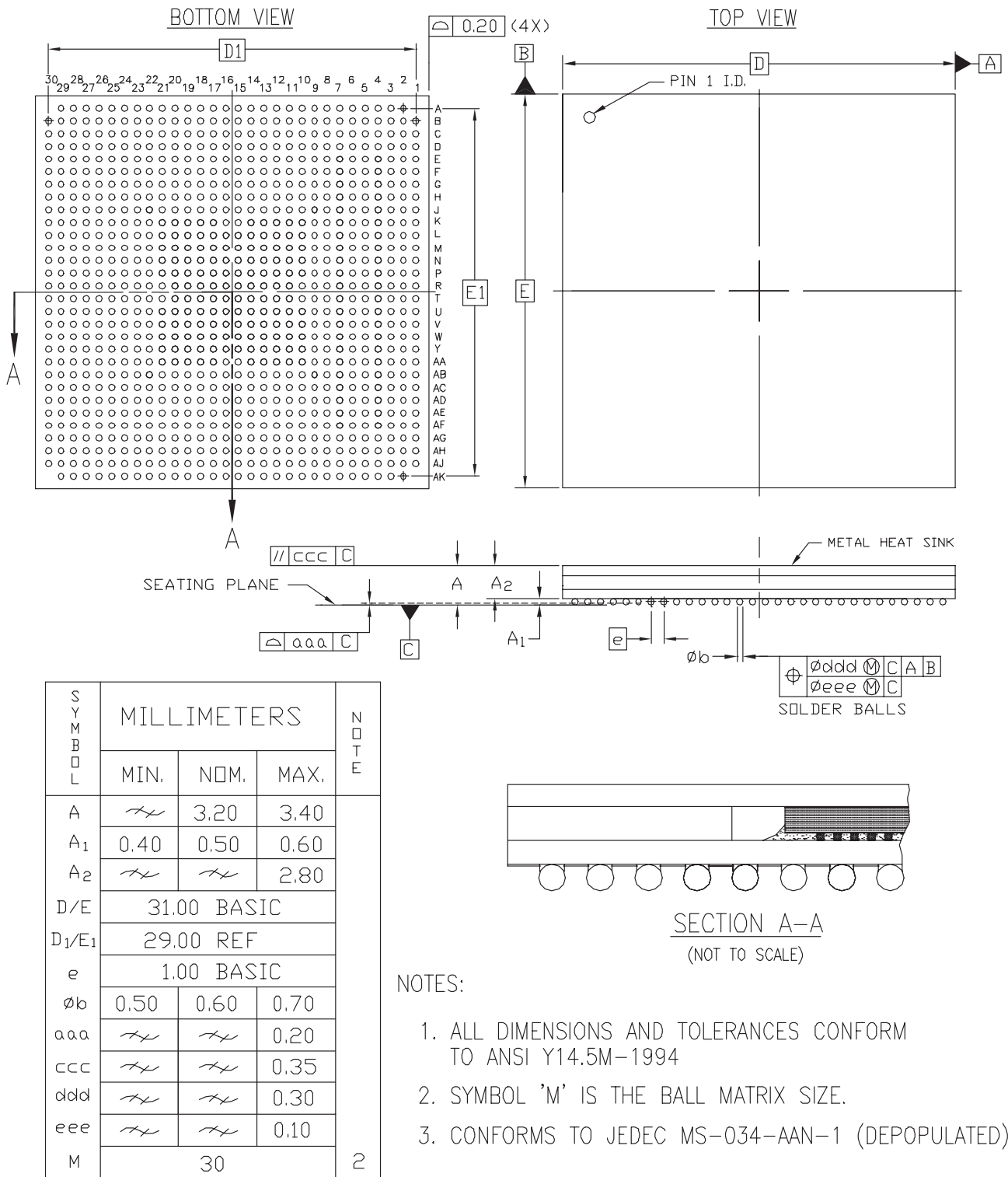


Figure 4-25: FF896 Flip-Chip Fine-Pitch BGA Package

FF1152 Flip-Chip Fine-Pitch BGA Package (1.00 mm Pitch)

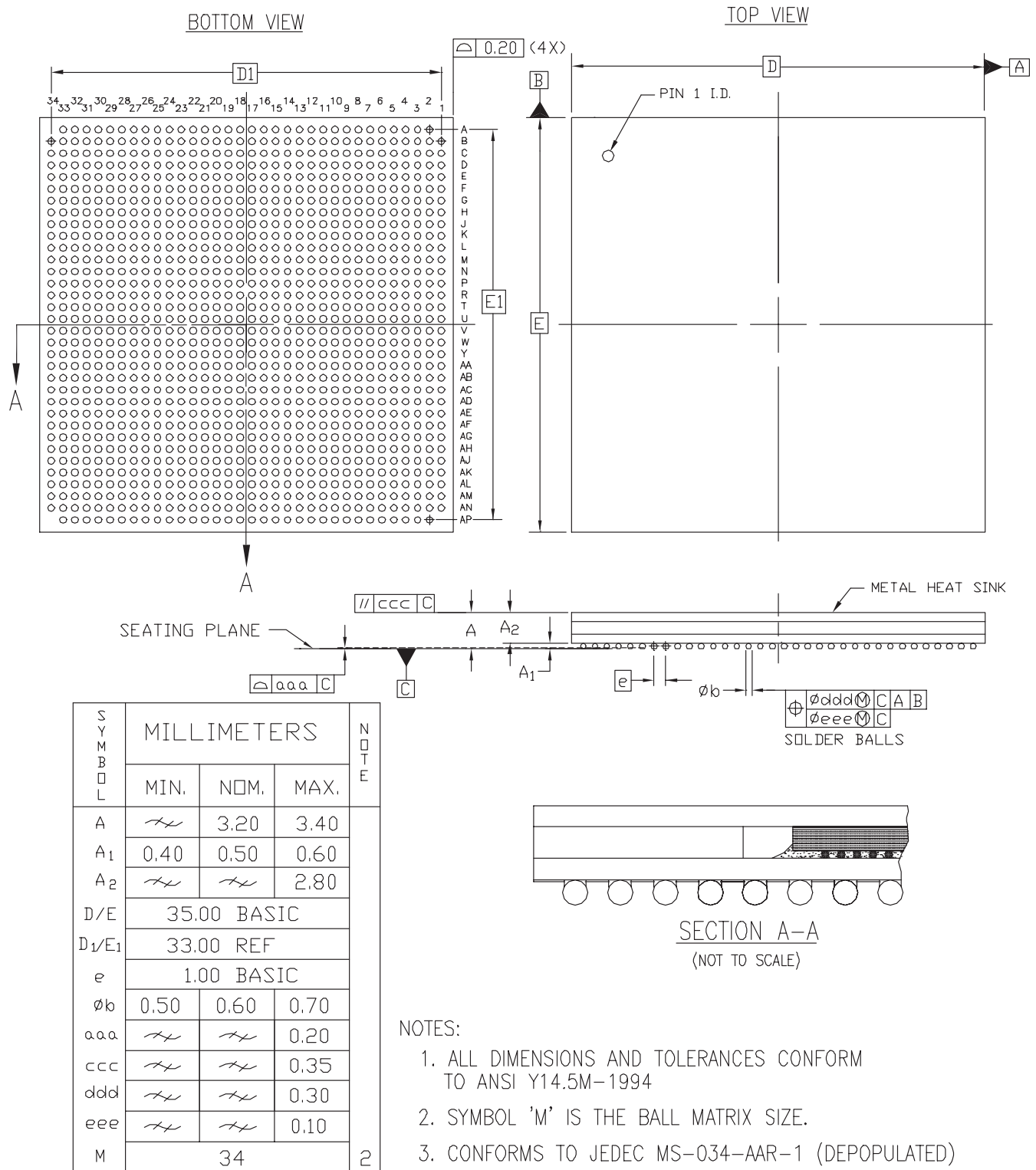


Figure 4-26: FF1152 Flip-Chip Fine-Pitch BGA Package

FF1517 Flip-Chip Fine-Pitch BGA Package (1.00 mm Pitch)

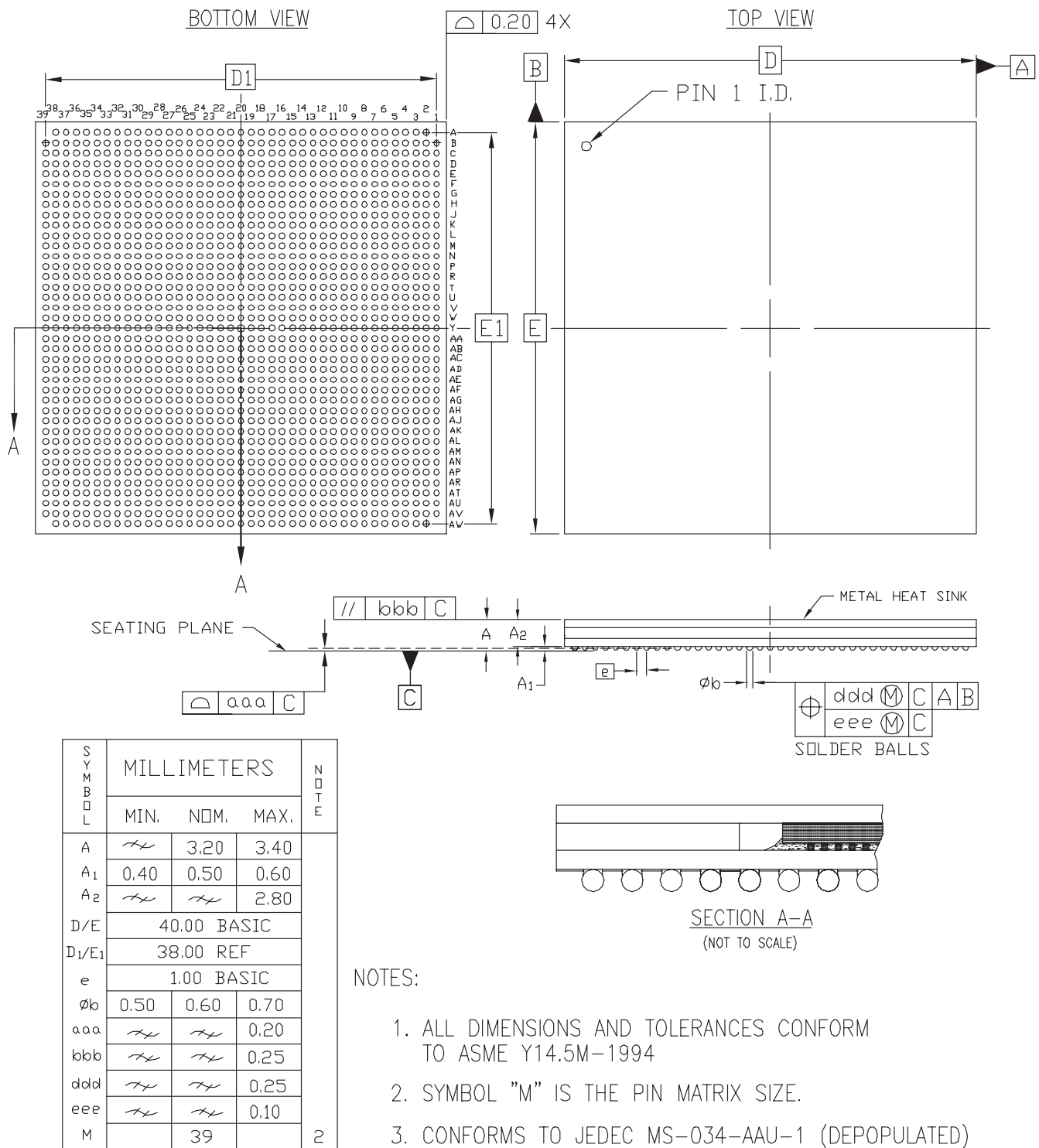


Figure 4-27: FF1517 Flip-Chip Fine-Pitch BGA Package

BF957 Flip-Chip BGA Package (1.27 mm Pitch)

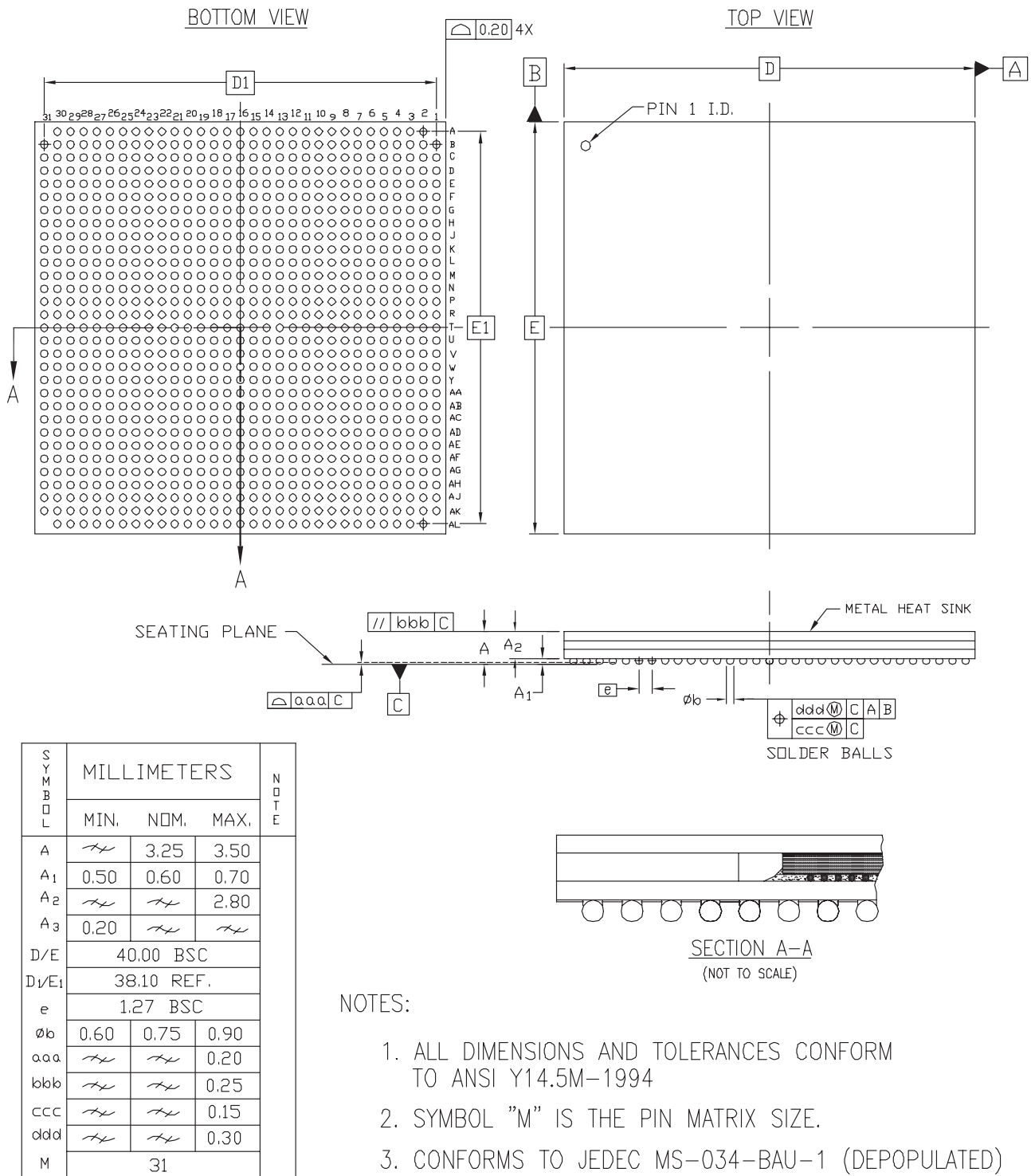


Figure 4-28: BF957 Flip-Chip BGA Package